

SML75HB06

Attributes:

- aerospace build standard
- high reliability
- lightweight
- metal matrix base plate
- AlN isolation


**Maximum rated values/
Electrical Properties**

Collector-emitter Voltage		V _{ces}	600	V
DC Collector Current T _c =75C T _c =25C	I _c , nom I _c	75 100	A	
Repetitive peak Collector Current tp=1msec, T _c =75C	I _{cm}	150	A	
Total PowerDissipation T _c =25C	P _{tot}	260	W	
Gate-emitter peak voltage	V _{ges}	+/-20	V	
DC Forward Diode Current	I _f	75	A	
Repetitive Peak Forward Current	I _{frm}	150	A	
I ² t value per diode V _r =0V, tp=10msec, T _{vj} =125C	I ² _t	500	A ² sec	
Isolation test voltage RMS, 50Hz, t=1min	V _{isol}	2500	V	

Collector-emitter saturation voltage I _c =75A, V _{ge} =15V, T _c =25C I _c =75A, V _{ge} =15V, T _c =125C	V _{ce(sat)}		1.95 2.2	2.45	V
Gate Threshold voltage V _{ce} =V _{ge} , T _{vj} =25C	V _{ge(th)}	4.5	5.5	6.5	V
Input capacitance f=1MHz, T _{vj} =25C, V _{ce} =25V, V _{ge} =0V	C _{ies}		3.2		nF
Reverse transfer Capacitance f=1MHz, T _{vj} =25C, V _{ce} =25V, V _{ge} =0V	C _{res}		0.3		nF
Collector emitter cut off current V _{ce} =600V, V _{ge} =0V, T _{vj} =25C V _{ce} =600V, V _{ge} =0V, T _{vj} =125C	I _{ces}	1 1	500	μ A	
Gate emitter cut off current V _{ce} =0V, V _{ge} =20V, T _{vj} =25C	I _{ges}		400	μ A	

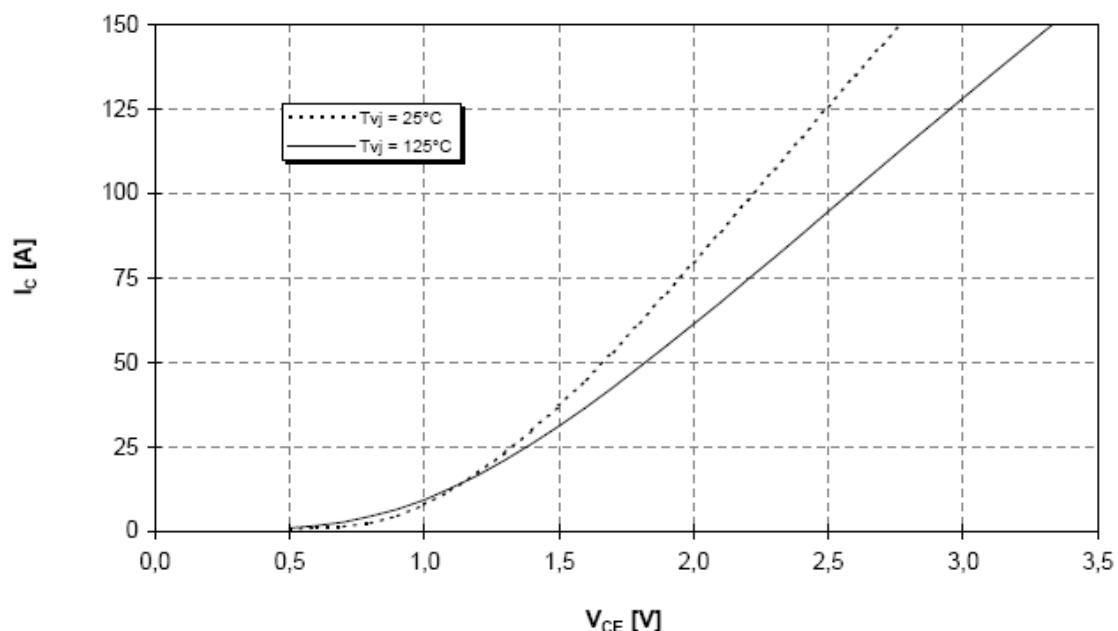
Turn on delay time	Ic=75A, Vcc=300V Vge=+/-15V,Rg=3Ω,Tvj=25C Vge=+/-15V,Rg=3Ω,Tvj=125C	t _{d,on}		63 65		nsec nsec
Rise time	Ic=75A, Vcc=300V Vge=+/-15V,Rg=3Ω,Tvj=25C Vge=+/-15V,Rg=3Ω,Tvj=125C	tr		22 1025		nsec nsec
Turn off delay time	Ic=75A, Vcc=300V Vge=+/-15V,Rg=3Ω,Tvj=25C Vge=+/-15V,Rg=3Ω,Tvj=125C	t _{d,off}		155 170		nsec nsec
Fall time	Ic=75A, Vcc=300V Vge=+/-15V,Rg=3Ω,Tvj=25C Vge=+/-15V,Rg=3Ω,Tvj=125C	t _f		20 35		nsec nsec
Turn energy loss per pulse	Ic=75A, Vce=300V, Vge=15V Rge=2.7Ω, Tvj=125C, L=35nH	E _{on}		0.7		mJ
Turn off energy loss per pulse	Ic=75A, Vce=300V, Vge=15V Rge=Ω, Tvj=125C, L=30nH	E _{off}		2.4		mJ
SC Data	tp≤10μsec, Vge≤15V Tvj≤125C, Vcc=360V, Vce(max)- Vces-Lσdi/dT	I _{sc}		340		A
Stray Module inductance		L _{oce}		40		nH
Terminal-chip resistance		R _c		1.2		mΩ

Diode characteristics

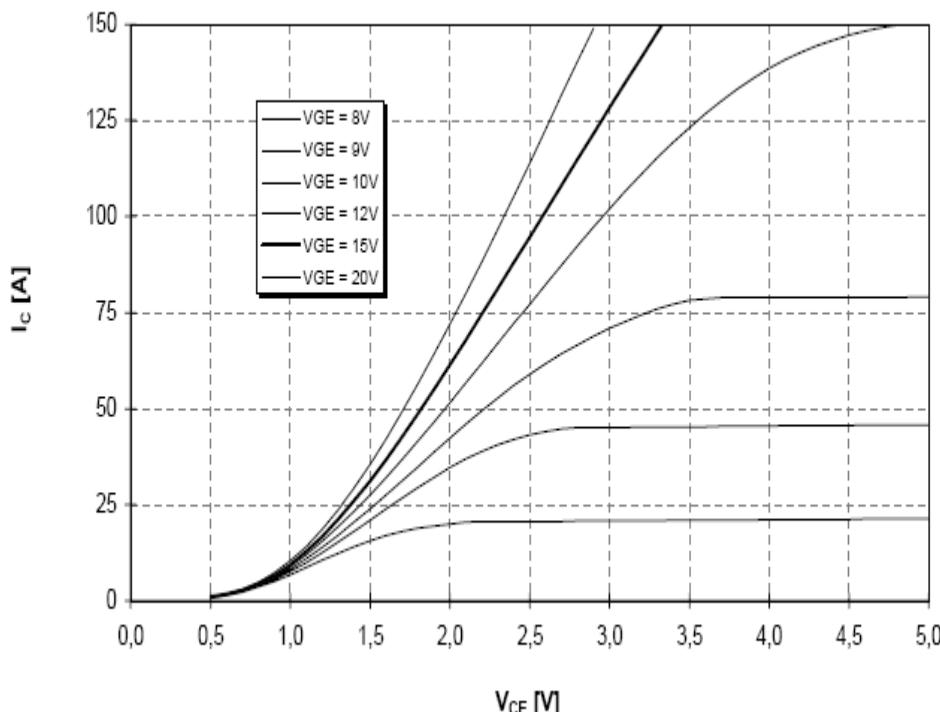
Forward voltage	Ic=75A, Vge=0V, Tc=25C Ic=75A, Vge=0V, Tc=125C	V _f		1.25 1.2	1.6	V
Peak reverse recovery current	If=75A, -di/dt=3000A/μsec Vce=300V, Vge=-10V, Tvj=25C Vce=300V, Vge=-10V, Tvj=125C	I _{rm}		95 115		A
Recovered charge	If=75A, -di/dt=3000A/μsec Vce=600V, Vge=-10V, Tvj=25C Vce=600V, Vge=-10V, Tvj=125C	Q _r		5.1 7.9		μC
Reverse recovery energy	If=75A, -di/dt=3000A/μsec Vce=600V, Vge=-10V, Tvj=25C Vce=600V, Vge=-10V, Tvj=125C	E _{rec}		.	2.3	mJ mJ

Thermal Properties**Min** **Typ** **Max**

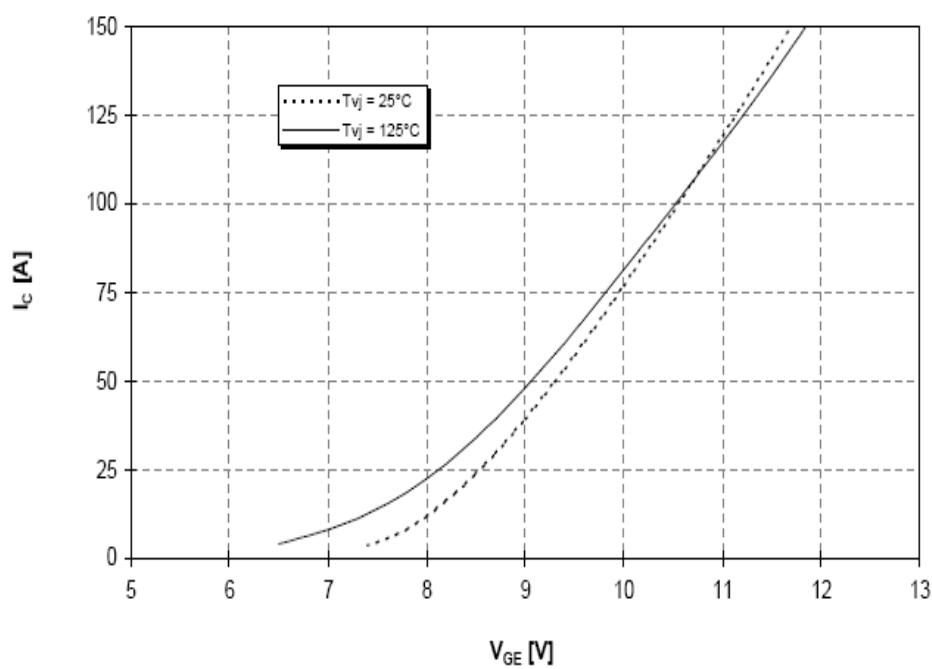
Thermal resistance junction to case	Igbt Diode	R_{0J-C}			0.48 0.89	K/W
Thermal resistance case to heatsink		R_{0C-hs}		0.03		K/W
Maximum junction temperature		T_{vj}			150	C
Maximum operating temperature		T_{op}	-55		125	C
Storage Temperature		T_{stg}	-55		125	C

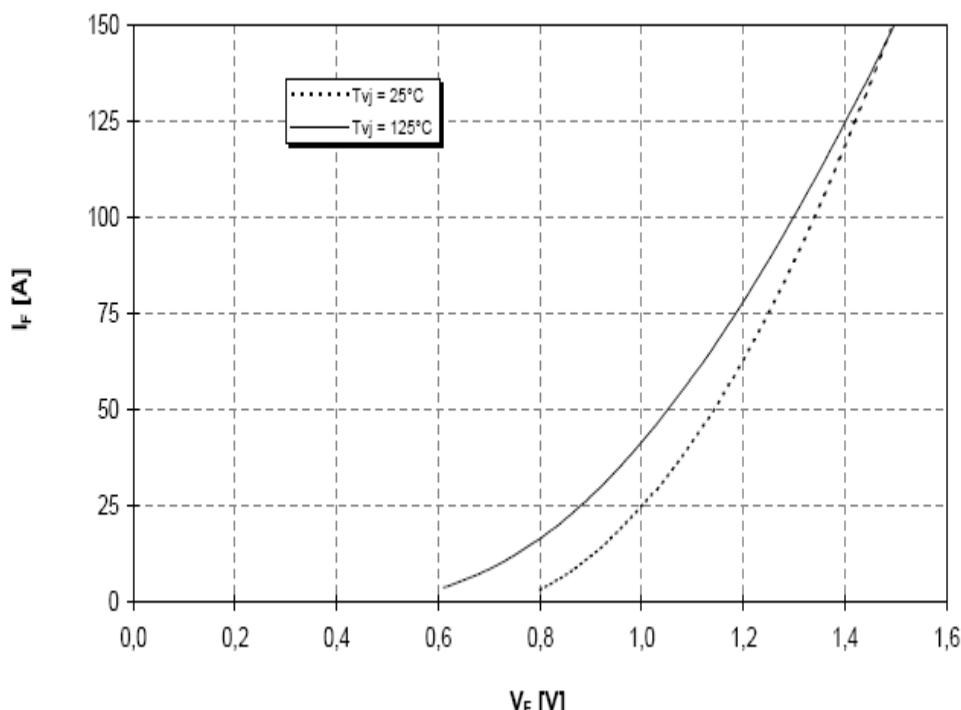
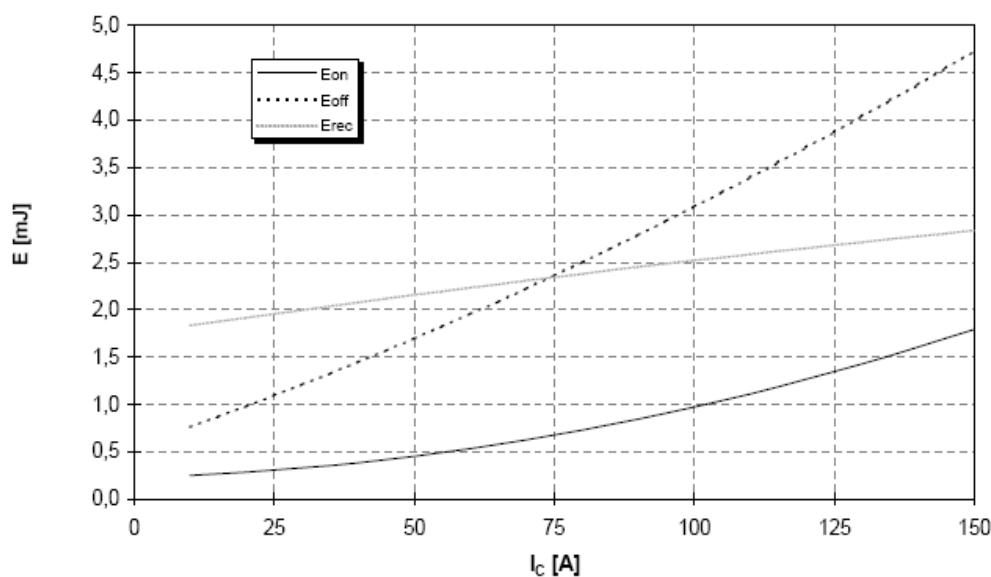
Output characteristic (typical) $V_{GE} = 15V$ 

Output characteristic (typical)

 $T_{vj} = 125^{\circ}\text{C}$ 

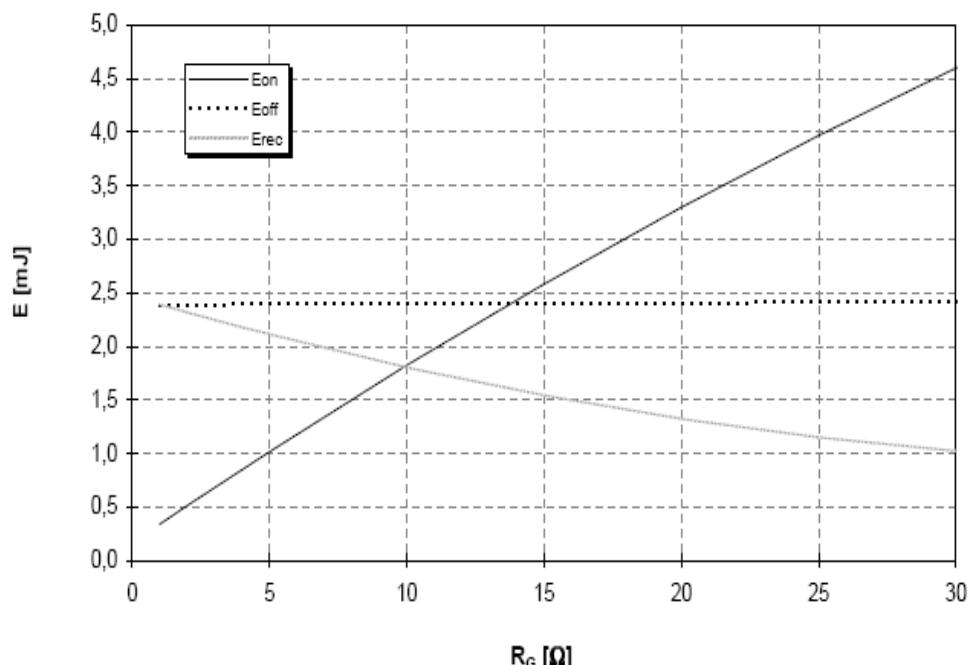
Transfer characteristic (typical)

 $V_{CE} = 20\text{V}$ 

Forward characteristic of inverse diode (typical)

Switching losses (typical)
 $R_{G,ON} = 3,0\Omega$, $R_{G,OFF} = 3,0\Omega$, $V_{CC} = 300V$, $T_{vj} = 125^\circ C$


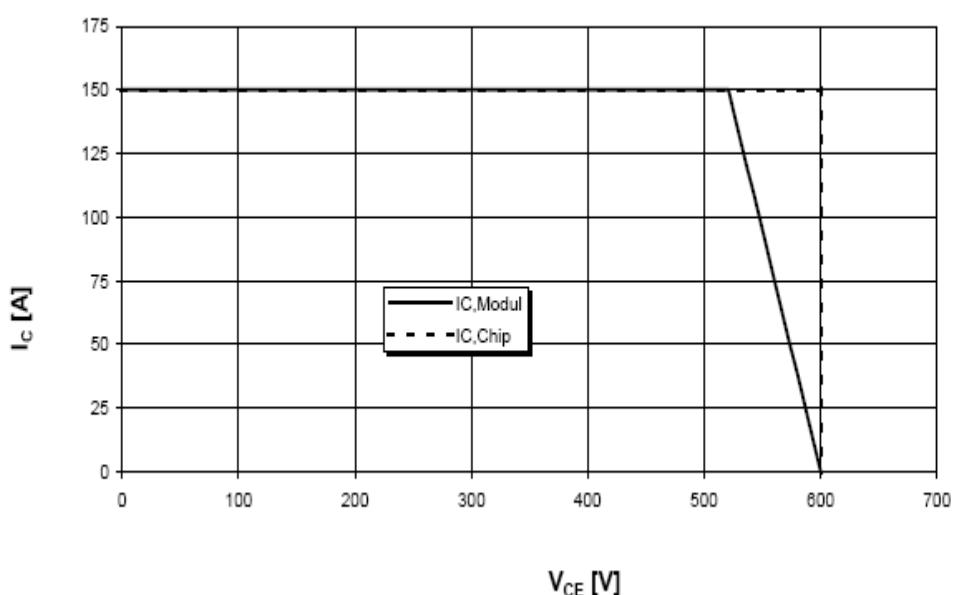
Switching losses (typical)

$I_C = 75A, V_{CC} = 300V, T_{vj} = 125^\circ C$

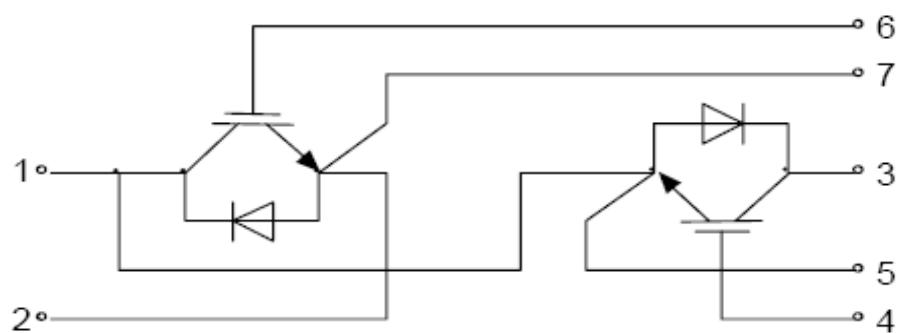
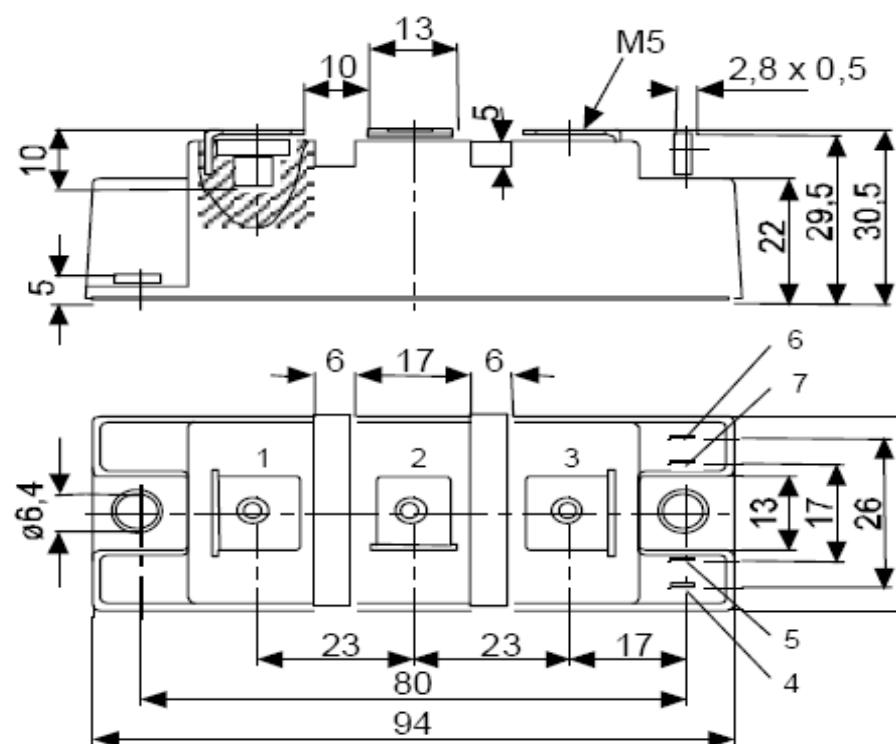


Reverse bias safe operation area (RBSOA)

$V_{GE} = +15V, R_{G,off} = 3,0\Omega, T_{vj} = 125^\circ C$



Package outline / Circuit diagram



CIRCUIT DIAGRAM